

CLAIMS:

1. A semiconductor encapsulating epoxy resin composition comprising
- 5 (A) an epoxy resin,
(B) a phenolic resin curing agent,
(C) a molybdenum compound, and
(D) 300 to 900 parts by weight per 100 parts by weight of components (A) and (B) combined of an inorganic filler,
- 10 wherein nitrogen atoms are contained in component (A) and/or component (B) in an amount of 1.5 to 20% by weight based on the weight of components (A) and (B) combined.
2. The epoxy resin composition of claim 1 wherein
- 15 component (B) is a phenolic resin containing nitrogen atoms in its skeleton in the form of a triazine ring structure, guanamine skelton or cyanurate skelton.
3. The epoxy resin composition of claim 1 wherein
- 20 component (A) is an epoxy resin containing nitrogen atoms in its skeleton in the form of a triazine ring structure, guanamine skelton or cyanurate skelton.
4. The epoxy resin composition of claim 1 wherein the
- 25 molybdenum compound (C) is zinc molybdate.
5. The epoxy resin composition of claim 2 wherein the molybdenum compound (C) is zinc molybdate supported on an inorganic filler.
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6. A semiconductor device encapsulated with a cured product of the epoxy resin composition of claim 1.

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